

52804

06-07-2004



102759259

Form PTO-1595
(Rev. 10/02)
OMB No. 0651-0027 (exp. 6/30/2)

EET U.S. DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office
501.43750X00

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
**CHAKIHARA, HIRAKU
NOGUCHI, MITSUHIRO
TADOKORO, MASAHIRO
WADA, NAONORI
NISHIDA, AKIO**

2. Name and address of receiving party(ies)
Name: **RENESAS TECHNOLOGY CORP.**

Internal Address: _____
Address: _____

Street Address: **4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan**

City: _____ State: _____ Zip: _____

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____

Execution Date: **Feb. 27, 2004; Mar. 10, 2004; Feb. 27, 2004; Mar. 1, 2004; Mar. 4, 2004.**

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: **Feb. 27, 2004; Mar. 10, 2004; Feb. 27, 2004; Mar. 1, 2004; Mar. 4, 2004.**

A. Patent Application No.(s)

10/8555592

B. Patent Registration No.(s)

Additional number(s) attached Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Antonelli, Terry, Stout & Kraus, LLP**

Internal Address:

**1300 North Seventeenth Street
Suite 1800
Arlington, VA 22209
USA**

City: _____ State: _____ Zip: _____

6. Total number of applications and patents involved 1

7. Total fee (37 CFR 3.41)..... \$40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

01-2135

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William I. Solomon, Reg# 28,565

Name of Person Signing

Signature

05/28/2004

Date

Total number of pages including cover sheet, attachments, and document: 1 2

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patent & Trademarks, Box Assignments
Washington, D.C. 20231

17510 U.S. PTO
10/855598
052804

06/02/2004 EHAILE1 00000033 10855598

03 FD:6021

40.00 0P

PATENT
REEL: 015405 FRAME: 0375

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp., a corporation organized under the laws of Japan, located at 4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A METHOD OF MANUFACTURING A SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Technology Corp., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

- | | | | |
|-----|--------------------------|-------------------|-----------------------------|
| 1) | <u>Hiraku Chakihara</u> | Hiraku CHAKIHARA | <u>27 / February / 2004</u> |
| 2) | <u>Mitsuhiro Noguchi</u> | Mitsuhiro NOGUCHI | <u>10 / March / 2004</u> |
| 3) | <u>Masahiro Tadokoro</u> | Masahiro TADOKORO | <u>27 / February / 2004</u> |
| 4) | <u>Naonori Wada</u> | Naonori WADA | <u>1 / March / 2004</u> |
| 5) | <u>Akio Nishida</u> | Akio NISHIDA | <u>4 / March / 2004</u> |
| 6) | _____ | | _____ |
| 7) | _____ | | _____ |
| 8) | _____ | | _____ |
| 9) | _____ | | _____ |
| 10) | _____ | | _____ |